

(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau



(43) International Publication Date
23 December 2004 (23.12.2004)

PCT

(10) International Publication Number
WO 2004/111581 A2

(51) International Patent Classification⁷:

G01F 23/00

(81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.

(21) International Application Number:

PCT/EP2004/050909

(22) International Filing Date: 25 May 2004 (25.05.2004)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

03013632.9

16 June 2003 (16.06.2003) EP

(84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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Published:

— without international search report and to be republished upon receipt of that report

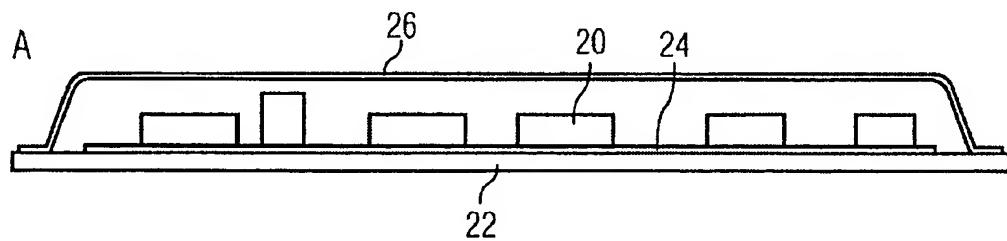
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(54) Title: A METHOD FOR MANUFACTURING AN ELECTRONIC ARRANGEMENT AND AN ELECTRONIC CIRCUIT ARRANGEMENT



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(57) Abstract: A method for manufacturing an electronic circuit device in a motor vehicle fuel tank, the method arranging one or more electronic modules on a substrate, and fixating the substrate with respect to a fuel tank wall. To obtain a permanent separation between electronics and fuel, which is easy to implement, and allows to keep the electronics close to the fuel proper, the method according to the invention encapsulates the one or more electronic modules against the fuel by a cap that connects to the substrate whilst forming an encapsulated space that is separated from any fuel or vapour outside the encapsulated space. The electronic modules may provide various different functional principles, e.g. fuel level measuring or demand regulated fuel pump control.